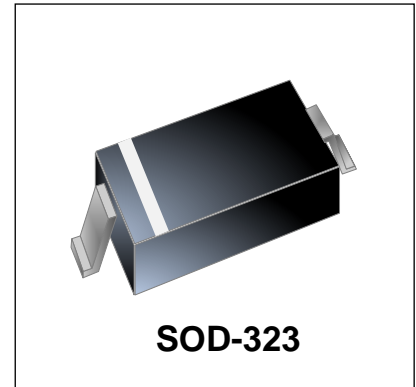


Features

- 450 Watts Peak Pulse Power per Line ($t_p = 8/20\mu s$)
- Protects one I/O or power line
- Low Clamping Voltage
- Working Voltage: 12V
- Low Leakage Current
- Ultra Low Capacitance: 1.0 pF Typical



IEC COMPATIBILITY (EN61000-4)

- IEC 61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5(Lightning) 15A (8/20 μs)

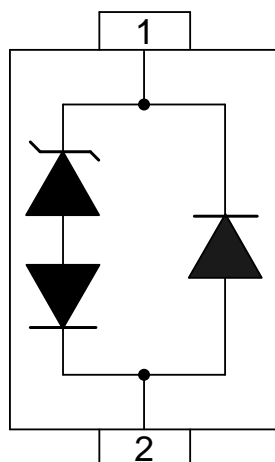
Mechanical Characteristics

- JEDEC SOD-323 package
- Packaging : Tape and Reel Per EIA 481
- Device Marking: Marking Code
- RoHS Compliant

Applications

- Ethernet - 10/100/1000 Base T
- Cellular Phones
- Handheld - Wireless Systems
- Personal Digital Assistant (PDA)
- USB Interface

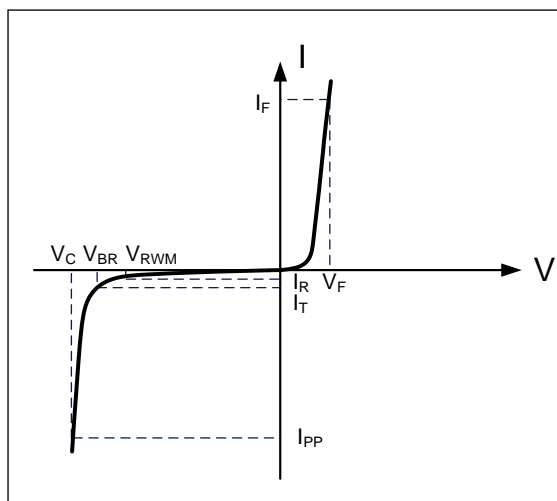
PIN Configuration



Absolute Maximum Rating			
Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{PP}	450	Watts
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{PP}	15	A
Operating Temperature	T_J	-55 to + 150	°C
Storage Temperature	T_{STG}	-55 to +150	°C

Electrical Parameters (T=25°C)

Symbol	Parameter
I_{PP}	Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_F	Forward Current
V_F	Forward Voltage @ I_F



Electrical Characteristics

WS12DLC						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				12	V
Reverse Breakdown Voltage	V_{BR}	$I_T=1mA$	13.3		18	V
Reverse Leakage Current	I_R	$V_{RWM}=12V, T=25^\circ C$			100	nA
Forward Voltage	V_F	$I_F=10mA$	0.5		1.0	V
Clamping Voltage	V_C	$I_{PP}=15A, t_p=8/20\mu s$		26	30	V
Dynamic Resistance ^{1,2}	R_{DYN}	TLP=0.2/100ns		0.5		Ω
ESD Clamping Voltage ¹	V_C	$I_{PP} = 4A, t_p = 0.2/100ns$ (TLP)		17.3		V
ESD Clamping Voltage ¹	V_C	$I_{PP} = 16A, t_p = 0.2/100ns$ (TLP)		23.3		V
Junction Capacitance	C_j	$V_R = 0V, f = 1MHz$		1	1.35	pF

Notes : 1、 TLP Setting : $t_p=100ns, t_r=0.2ns, I_{TLP}$ and V_{TLP} sample window: $t_1=70ns$ to $t_2=90ns$.
 2、 Dynamic resistance calculated from $I_{PP}=4A$ to $I_{PP}=16A$ using "Best Fit".

Typical Characteristics

Figure 1: Peak Pulse Power vs. Pulse Time

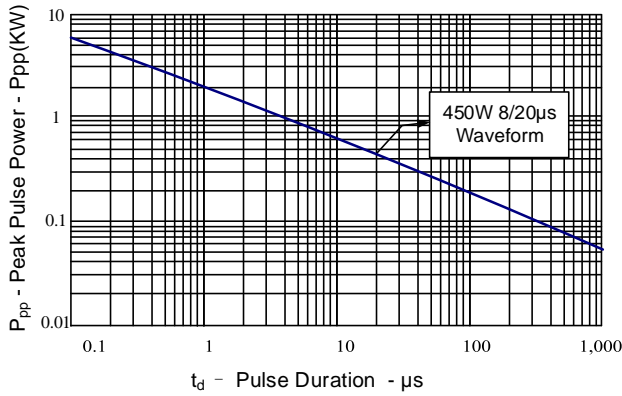


Figure 2: Power Derating Curve

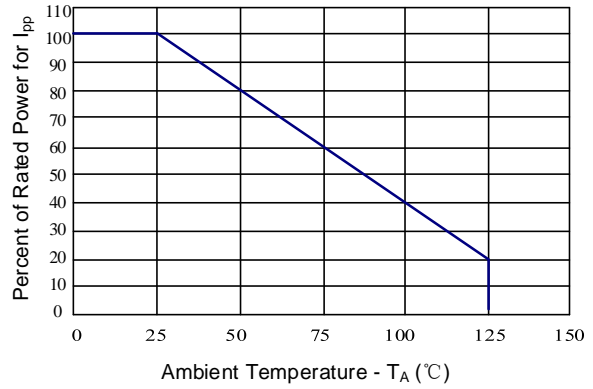


Figure 3: Clamping Voltage vs. Peak Pulse Current

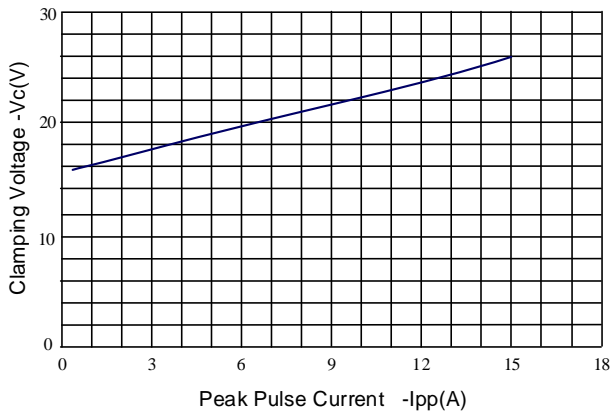


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

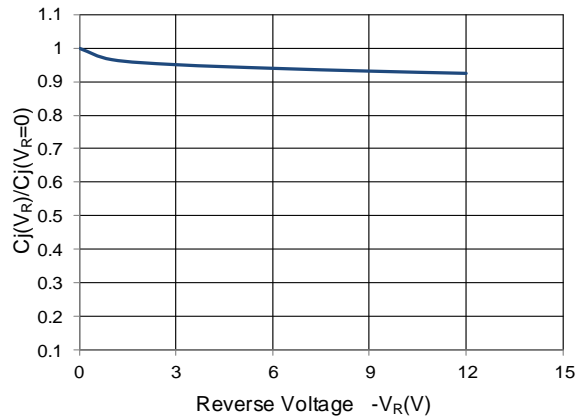


Figure 5: 8/20µs Pulse Waveform

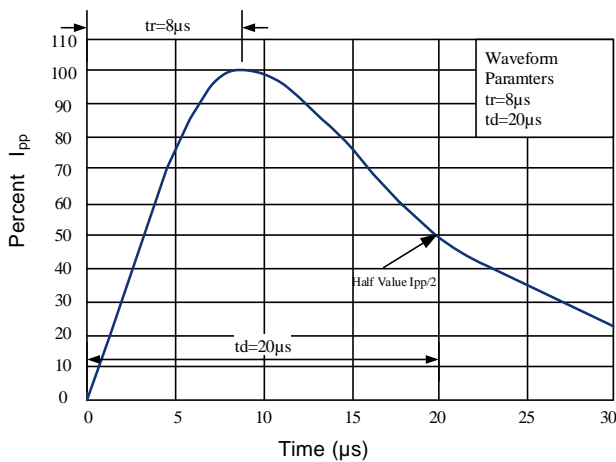
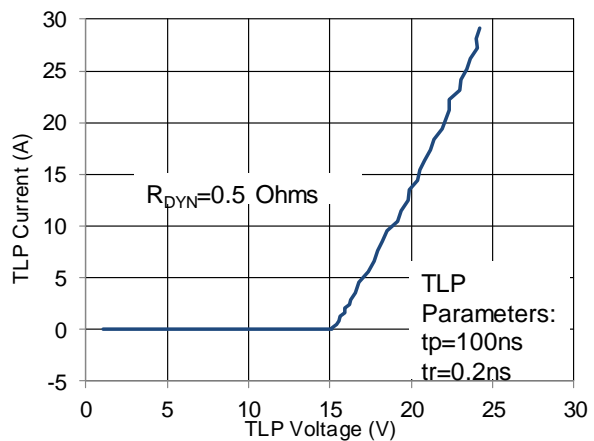
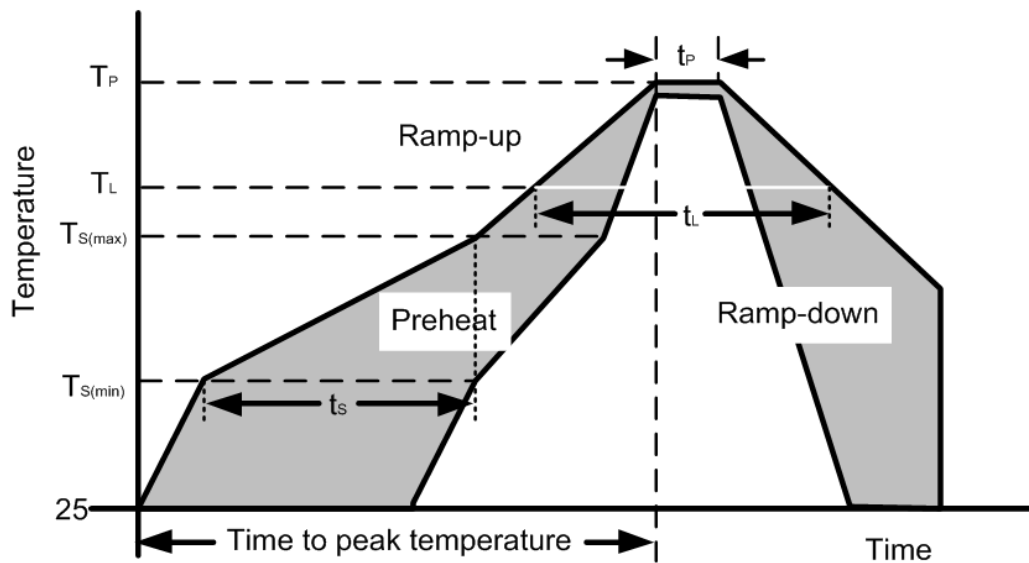


Figure 6: TLP Positive I-V Curve



Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	Temperature Min ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 190 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
$T_{s(max)}$ to T_L — Ramp-up Rate		5°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_P)		260+0/-5 °C
Time within actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes Max.
Do not exceed		280°C



Outline Drawing – SOD-323

PACKAGE OUTLINE

SOD-323

DIMENSIONS				
SYMBOL	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.52	1.80	0.060	0.071
B	0.25	0.40	0.010	0.016
C	2.46	2.71	0.097	0.107
D	0.80	1.16	0.031	0.046
E	1.11	1.40	0.044	0.055
F	0.08	0.20	0.003	0.008
L	0.475 REF		0.019REF	
L1	0.25	0.40	0.010	0.016
H	0.00	0.10	0.000	0.004

MOUNTING PAD

Notes:
Controlling Dimension: Millimeter.

Marking Codes

Part Number	WS12DLC
Marking Code	

Package Information

Qty: 3k/Reel

CONTACT INFORMATION

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For additional information, please contact your local Sales Representative.

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Specifications are subject to change without notice.
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.
Users should verify actual device performance in their specific applications.